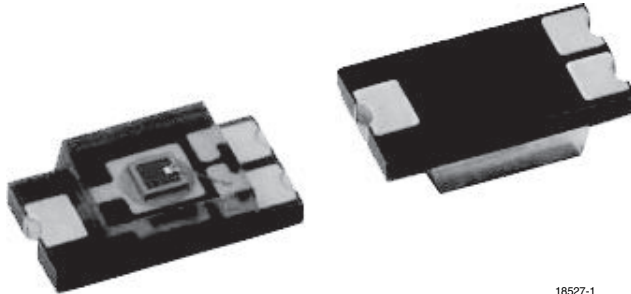


## Ambient Light Sensor



18527-1

### DESCRIPTION

TEMD6010FX01 ambient light sensor is a PIN photodiode with high speed and high photo sensitivity in a clear, surface mount plastic package. The detector chip has 0.27 mm<sup>2</sup> sensitive area. It is sensitive to visible light much like the human eye and has peak sensitivity at 540 nm.

### FEATURES

- Package type: surface mount
- Package form: 1206
- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm<sup>2</sup>): 0.27
- AEC-Q101 qualified
- High photo sensitivity
- Adapted to human eye responsivity
- Supression filter for near infrared radiation
- Angle of half sensitivity:  $\phi = \pm 60^\circ$
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### APPLICATIONS

- Automotive sensors
- Ambient light sensors
- Backlight dimming
- Mobil phones
- Notebooks
- Computers

### PRODUCT SUMMARY

COMPONENT	$I_{ra}$ (μA)	$\phi$ (deg)	$\lambda_{0.5}$ (nm)
TEMD6010FX01	0.04	$\pm 60$	430 to 610

#### Note

- Test conditions see table "Basic Characteristics"

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TEMD6010FX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206

#### Note

- MOQ: minimum order quantity

### ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	16	V
Power dissipation		$P_V$	100	mW
Junction temperature		$T_j$	100	$^\circ\text{C}$
Operating temperature range		$T_{amb}$	- 40 to + 100	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	- 40 to + 100	$^\circ\text{C}$
Soldering temperature	Acc. reflow solder profile fig. 7	$T_{sd}$	260	$^\circ\text{C}$
Thermal resistance junction/ambient	Soldered on PCB with pad dimensions: 4 mm x 4 mm	$R_{thJA}$	450	K/W

<b>BASIC CHARACTERISTICS</b> ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$ , $E = 0\text{ lx}$	$V_{(BR)}$	16			V
Reverse dark current	$V_{CE} = 10\text{ V}$ , $E = 0\text{ lx}$	$I_{ro}$		0.1	5	nA
Diode capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ lx}$	$C_D$		60		pF
	$V_R = 5\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ lx}$	$C_D$		24		pF
Reverse light current	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 550\text{ nm}$ , $V_R = 5\text{ V}$	$I_{ra}$		1		$\mu\text{A}$
	$E_V = 100\text{ lx}$ , CIE illuminant A, $V_R = 5\text{ V}$	$I_{ra}$	0.03	0.04	0.09	$\mu\text{A}$
Temperature coefficient of $I_{ra}$	$E_V = 100\text{ lx}$ , CIE illuminant A, $V_R = 5\text{ V}$	$TK_{I_{ra}}$		0.2		%/K
Angle of half sensitivity		$\phi$		$\pm 60$		deg
Wavelength of peak sensitivity		$\lambda_p$		540		nm
Range of spectral bandwidth		$\lambda_{0.5}$		430 to 610		nm

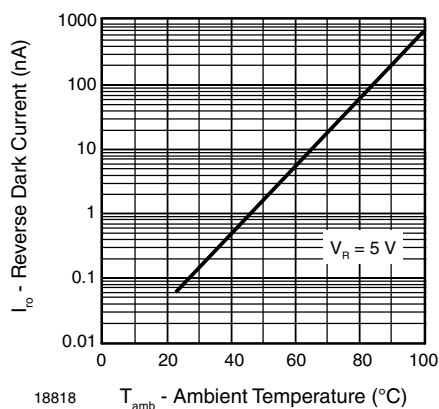
**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

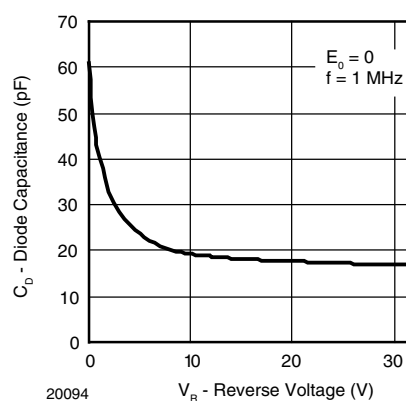


Fig. 3 - Diode Capacitance vs. Reverse Voltage

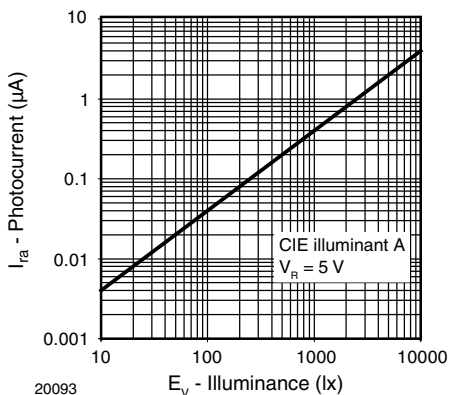


Fig. 2 - Reverse Light Current vs. Illuminance

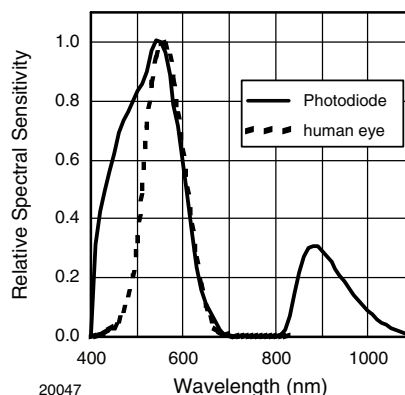


Fig. 4 - Relative Spectral Sensitivity vs. Wavelength

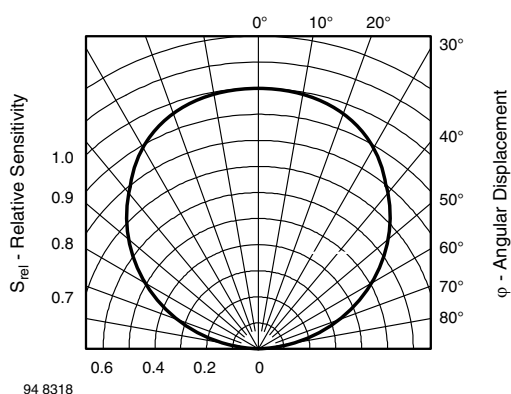


Fig. 1 - Relative Radiant Sensitivity vs. Angular Displacement

## REFLOW SOLDER PROFILE

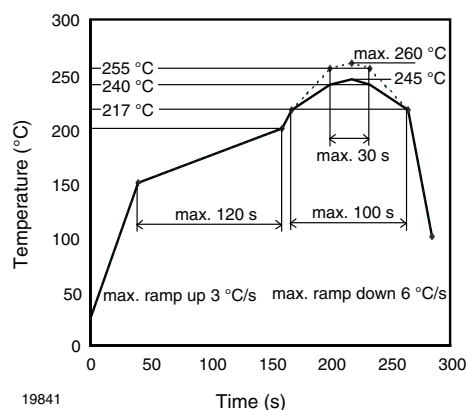
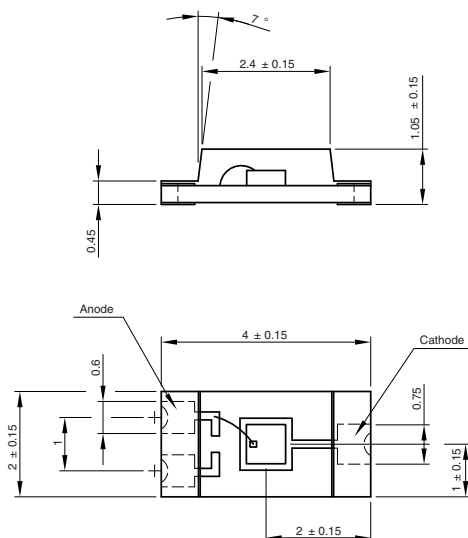
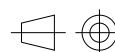


Fig. 5 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

### PACKAGE DIMENSIONS in millimeters



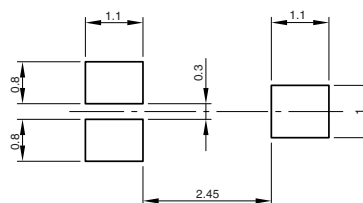
Drawing-No.: 6.541-5080.01-4  
Issue: 1; 31.08.09  
21884



technical drawings  
according to DIN  
specifications

Not indicated tolerances  $\pm 0.1$

Recommended solder pad  
Footprint



## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ ,  $RH < 60\%$

## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %.





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